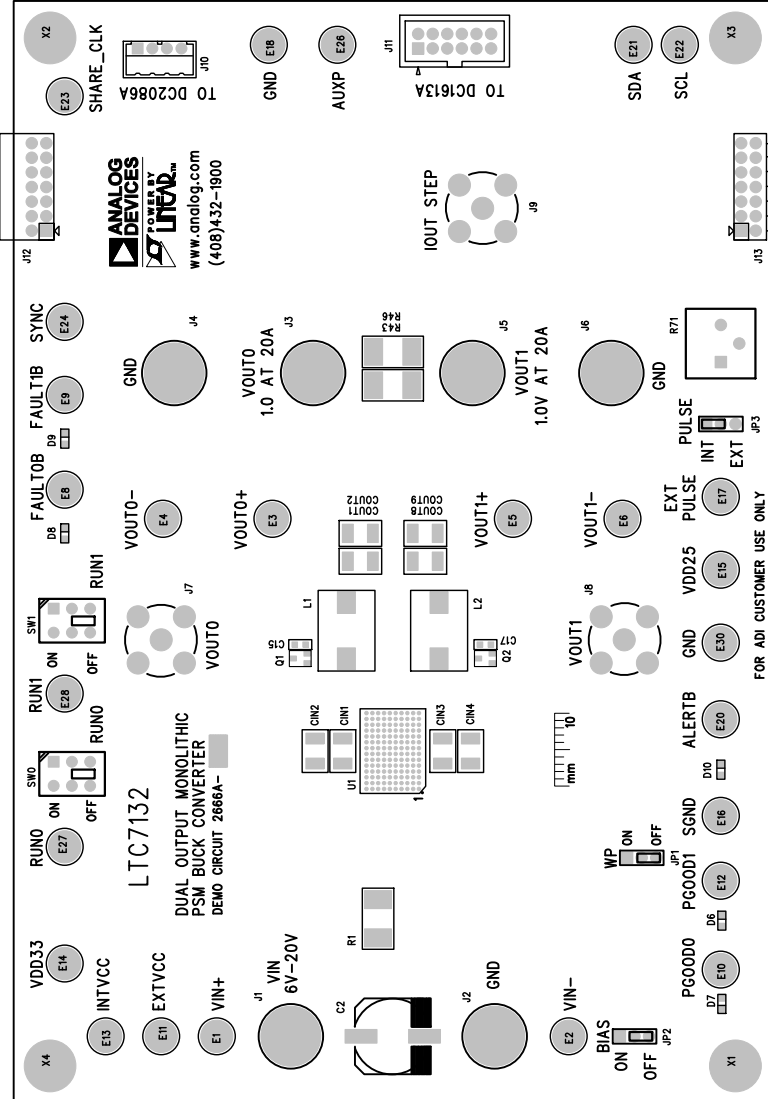
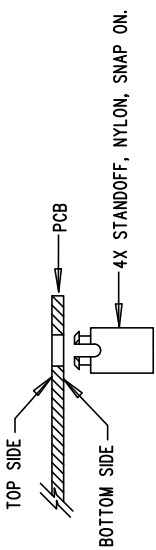


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG. DATE
-	3	PRODUCTION	GINA L. 6-19-18



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANLIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		ANALOG DEVICES CORPORATION	
PCB DES.	HZ	1630 MCCARTHY BLVD MILLITAS, CA 95035 PH: (408)432-1900 WWW.ANALOG.COM	
APP ENG.	GL	FOR ADI CUSTOMER USE ONLY	
		TITLE: TOP ASSEMBLY DRAWING	
		DUAL OUTPUT MONOLITHIC PSM BUCK CONVERTER	
SCALE	= NONE	SIZE	IC NO. LTC7132EY
			REV. 3
			N/A DEMO CIRCUIT 2666A
			FILENAME: DC2666A-2.PCB
			SHT 1 OF 2